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Specification number: EQM08-1KC-E185K14

Date of issue: 10 May, 2018

Multilayer ceramic Chip capacitor specification

Product Part No CM03X5R105M16AH

(Recipient stamp column) Please send back with recipient stamp or signature here.

This specification would be invalidated unlesse sent back within a year after issue date of this specification.

RoHS Compliant

Kyocera Corporation Capacitor Division



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Date	Contents	PREPD.	CHKD.	CHKD.	APPD.
2018/05/10	NEW				
	Date 2018/05/10				



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Characteristic	K/C Supplier Part No	Remarks
(5R	CM03X5R105M16AH	



1.Scope

This specification sheet shall be applied to multilayer ceramic chip capacitors;Kyocera CM series.

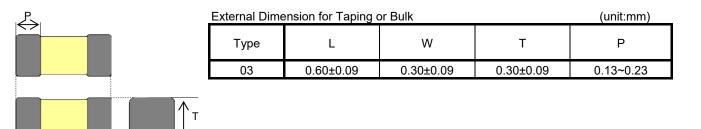
2.Nomenclature

<u>CM</u>						<u>A</u>	
Series	(1)	(2)	(3)	(4)	(5)	(6)	(7)

(1) : Size

- (2) : Temperature Characteristics
- (3) : Capacitance
- (4) : Tolerance
- (5) : Rated Voltage
- (6) : External Electrode
- (7) : Packaging

(1)External Dimensions(Size)



(2)Temperature Characteristics

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Characteristics Applied voltage		Change in capacitance	Operating temperature range	Reference
X5R	No applied voltage	Within +/-15%	-55°C~+85°C	25°C



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(3)Capacitance Value

Capacitance is indicated by three numbers and a letter (see example as follows). The first and second digits indicate the first two significant figures, and the final digit is a base 10 logarithmic multiplier in picofarads.

(Ex.)	
Code	Capacitance
105	1,000,000pF

(4)Tolerance

Code	М
Tolerance	±20%

(5)Rated Voltage

Code	16
Voltage	16Vdc

(6)Termination (External Electrode)

A: Nickel Barrier / Tin

(7) Packaging Configuration

Code	Packaging Configuration	Applying Size
Н	Taping(2mm Pitch. Φ180 Reel)	Refer to Taping specification

3. Operating temperature range

Refer to Item 2-(2)



4.Specifications and Test Methods

(Table 1-1)

Item		Specification X5R	Measuring Conditions
Capacitance		Within specified tolerance value	High Temperature Treatment (Table 2)
tanδ		Refer to (Table 3)	C≤10µF Measuring frequency 1kHz±10% Measuring voltage Refer to (Table 3)
(*1)Insulation	Resistance	Refer to (Table 3)	Measure after charging with the rated voltage within 1 minutes at room conditions.
(*1)Dielectric	Strength	No problem observed	Applying 2.5 times of the rated voltage for 1 to 5 seconds.
Appearance		No serious defect	Under Microscope
End Termina adherence	tion	No evidence of peeling on the end termination	After soldering chip capacitors on glass epoxy boards and applying 2N(0.2Kgf) as shown by the arrow mark in the sketch peeling or any sign of peeling should not be found on end terminations. (Refer to Fig.1)
Resistance to Vibration	Appearance	No serious defect	Perform High Temperature Treatment (Table 2) , then measure the initial capacitance and tan $\delta.$
Vibration	Capacitance Variation	Within specified tolerance value	Vibration frequency:10 to 55 (Hz) Swing width :1.5mm Sweep :10→55→10 Hz/1min
	tanδ	Satisfies initial specified value	Sweep :10→55→10 Hz/1min x,y,z axis 2 hours/each Total 6 hours
			(Refer to Fig.2)
Resistance to	Appearance	No serious defect	Perform High Temperature Treatment (Table 2) , then measure the initial capacitance and tan δ .
Solder Leaching	Capacitance Variation	Within ±7.5%	After dipped molten solder,
	tanδ	Satisfies initial specified value	at 260±5°C for 10±0.5 seconds and kept at room conditions for 24±2 hours,
	(*1)Insulation Resistance	Within specified tolerance value	measure and check the specifications.
	(*1)Dielectric Strength	Resist without problem.	*Pre-heat before immersion 1st: 80°C to 100°C for 120sec. 2st:150°C to 200°C for 120sec.
Solderability		Coverage >= 90% Each termination end	Soaking Condition <sn-3ag-0.5cu> 245±5°C 3±0.5sec. <sn63 solder=""> 235±5°C 2±0.5sec.</sn63></sn-3ag-0.5cu>





	lt a va	Specification	Manageming Conditions		
	Item	X5R	Measuring Conditions		
Temperature Cycling	Appearance	No serious defect	Perform High Temperature Treatment (Table 2) , then measure the initial capacitance and tan δ .		
	Capacitance Variation	Refer to (Table 4)	<cycle></cycle>		
	tanδ	Satisfies initial specified value	–Room temperature (3 minutes) - Lowest operating temperature (30 minutes) – Room temperature (3 minutes) –		
	(*1)Insulation Resistance	Refer to (Table 4)	Highest operating temperature (30 minutes). After 5 cycles of the above, keep at 150+0/-10°C		
	(*1)Dielectric Strength	Resist without problem	for 1 hour and then let sit for 24±2 hours at room temperature, then measure. (Refer to Fig.2)		
Load Humidity Resistance	Appearance	No serious defect	Perform High Temperature Treatment (Table 2) , then measure the initial capacitance and tanδ.		
INESISIAILE	Capacitance Variation	Refer to (Table 4)	Apply rated voltage for 500+12/-0 hours in pre-condition at 40±2°C, humidity 90% to		
	tanδ	Less than 2 times of the initial value	95%RH.		
	(*1)Insulation Resistance	Refer to (Table 4)	After test , keep at 150+0/-10°C for 1 hour and then let sit for 24±2 hours at room temperature, then measure.		
High Temperature Life	Appearance	No serious defect	Perform High Temperature Treatment (Table 2) , then measure the initial capacitance and tan $\delta.$		
Test	Capacitance Variation	Refer to (Table 4)	Apply voltage (Magnification of Applied voltage × Rated voltage) for 1000+12/-0 hours in		
	tanδ	Less than 2 times of the initial value	 pre-condition at the highest temperature. * Magnification of Applied voltage: refer to (Table 4) 		
	(*1)Insulation Resistance	Refer to (Table 4)	After test , keep at 150+0/-10°C for 1 hour and then let sit for 24±2 hours at room temperature, then measure.		
Bending Strength		No mechanical damage	Refer to Fig.3-1, Fig.3-2 The glass epoxy board is bent up 1mm in 10 sec.		

(*1) Insulation Resistance/Dielectric Strength; Charging or discharging current for these tests Is limited under 50mA.

(Table 2)

Initial		Keep chip capacitor at 150°C +0/-10°C for 1 hour, then leave chip capacitor at room temperature and normal humidity for 24±2 hours.
Treatment	Voltage Treatment	Pretreat capacitor for 1 hour at the same condition of the load test, then leave them at room condition for 24±2 hours before beginning the Load test.



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[Table3 Parts List]

Product Part No				tanδ	IR	Capacitance/
	L			[%]max	(initial) min	tanδ Measuring voltage
CM03X5R105M16AH	0.60±0.09	0.30±0.09	0.30±0.09	20.0%	5 MΩ	1.0±0.2Vrms

[Table4 test specifications]

Product Part No	Temperature Cycling		Load Humidity Resistance		High Temperature Life Test		
	Capacitance	IR	Capacitance	IR	Voltage	Capacitance	IR
	Variation	(Minimum	Variation	(Minimum	Bias [%]	Variation	(Minimum
		value)		value)			value)
CM03X5R105M16AH	±25.0%	5 ΜΩ	±25.0%	0.5 MΩ	100%	±25.0%	1 MΩ



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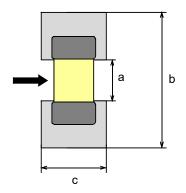


Fig.1 Substrate for adhesion strength test

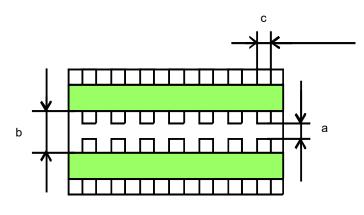


Fig.2 Substrate for temperature cycle test

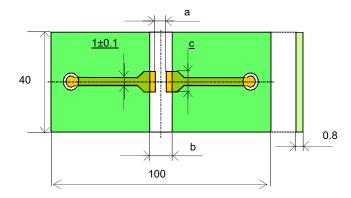


Fig.3-1 Substrate for bending test

type	а	b	С			
03	0.26	0.92	0.32			
glass epoxy board						

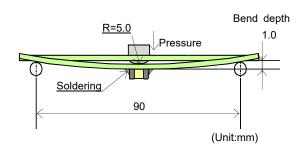
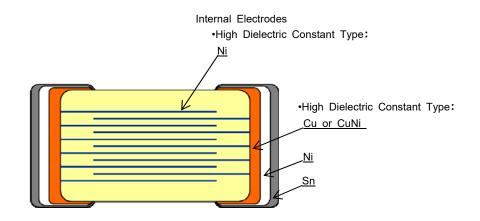


Fig.3-2 Testing status



[Structure]



[Production facility]

Kagoshima Kokubu plant



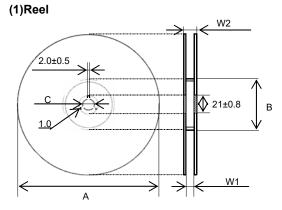
1.Application

This specification applies to paper carrier tape of Kyocera multi-layer ceramic chip capacitor.

2.Packing unit

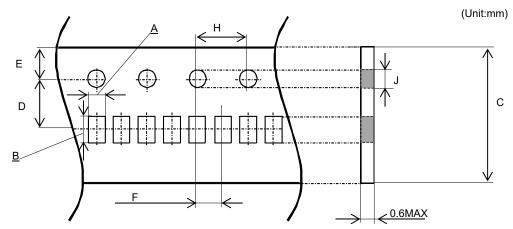
type thickness (unit:mm)	materi carrie	al of tape	width of carrier tape		Φ180 reel quantity	
	(unit:mm)	paper	Plastic	8mm	12mm	per reel
03	0.30±0.09	0	-	0	-	15000

3.Shape and dimentions



[Dimension]	Unit:mm		
	А	В	С
Ф180 reel (Code:H)	Ф180+0/-2.0	Ф60min	Ф13.0±0.5
	W1	W2	
Ф180 reel (Code:H)	10.0±1.5	16.5max	

(2)Carrier Tape



								(unit:mm)
Code	А	В	С	D	Е	F	Н	J
Tolerance Type	±0.03	±0.03	±0.3	±0.05	±0.1	±0.05	±0.1	+0.1/-0
03 Dimensions tolerance: ±0.09mm	0.42	0.72	8.0	3.5	1.75	2.0	4.0	φ1.5

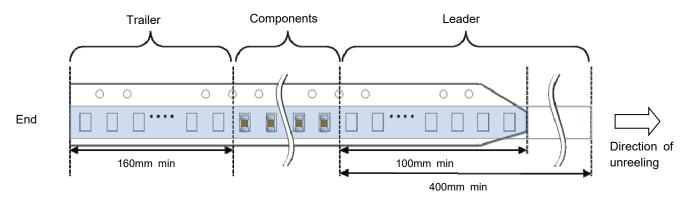


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4.Packing method

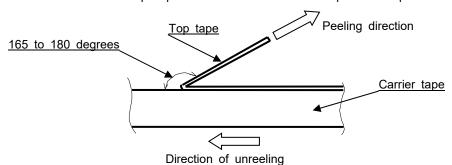
(1)Details of leader and trailer

①The tape will have a empty pocket at the leader and trailer of carrier tape.
②The tape end will not be stucked by glue in order to make it easier to peel off from reel.
③The feeding round hole will be on the right side against t leading direction.



(2)Heat pressure tape

①Peeling strength to be 0.1~0.7N when peeling off the top tape by following method.
②When peeling top tape off, the glue will be stuck to the top tape side.
③Chip capacitor will not stuck on heat pressure tape and will be free in the cavity.



The peel-off angle:165~180 degree against the surface of carrier tape. The peel-off speed:300mm/min.

(3)Carrier tape

OChip will not fall off from carrier tape or carrier tape will not be damaged by bending than within aradius of 25mm.

@The chip are inserted continuously without any empty pocket.

③Chip will not be mis-mounted because of too big clearance between components and cavity. Also the waste of carrier tape will not fill a nozzle hole of mouting machine.

5.Indication and packing

- OThere will be following indication on one side of the reel: "PART NUMBER", "LOT NUMBER", "QUANTITY", "DATE OF MANUFACTURE", "CUSTOMER'S NAME"
- [®]There will be following indication on the reel box: "PART NUMBER", "LOT NUMBER", "QUANTITY OF REEL", "DATE OF MANUFACTURE", "CUSTOMER'S NAME"
- ^③We adequately pack the box to prevent chip capacitor from any mechanical damage during transportation.



Precautions

Handling

1) Cracks may occur unless otherwise avoiding excessive stress to the capacitors by the load of an adsorption nozzle, and bending of a substrate at the time of mounting.

2) Please arrange the capacitor position where they don't have too much stress of board bending after mounting.

3) Please design that the form and size of the land pattern has suitable solder amount.

Otherwise cracks may occur. The recommended fillet height shall be 1/2 to 1/3 of the thickness of capacitors.

Circuit Design

 When AC voltage is superimposed on DC voltage, the zero-to-peak voltage shall not exceed the rated voltage. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency Voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
 Please use the capacitor below the maximum temperature.

When using the capacitor in a self-heating AC circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20 °C.

Resin coating

Please use the resin of low curing shrinkage type. (Otherwise cracks may occur).

Storage

1) When the components is stored in minimal packaging (a heat-sealed or chuck-type plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.

2) Keep storage place temperature +5 to +40 °C, humidity 20 to 70% RH.

3) The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.

4) Precautions 1) to 3) apply to chip capacitors packaged in carrier tapes and bulk cases.

5) The solderability is assured for 6 months from our shipping date if the above storage precautions are followed.

Application Restriction

Please consult with us before using a capacitor in the equipment which requires a high degree reliability (medical equipment, aerospace applications, nuclear equipment.) Malfunctions in medical, space, nuclear power or other vital equipment may result in death or great social losses. Capacitors designed specially with high reliability are used for the equipment above.

Export regulation

When the applying products relate the strategic materials which are provided in Foreign Exchange and Foreign Trade Act and Foreign Trade Management Law, the export license based on these laws are required.

Disposal

Please dispose the capacitors according to the relating laws about the waste treatment and cleaning. Safety application guideline and detailed information of electrical properties are also provided in Kyocera home page:

URL: http://www.kyocera.co.jp/electronic

Notice:

This specification shall guarantee only monolithic capacitors. Please make sure the performance of capacitors after mounted on the assembled product.

Any failures occurred being used out of this specification shall not be quaranteed.

This specification shall be applied to the products purchased through the regular sales routes, such as the sale offices, the subsidiaries and the distributors, etc.).





单击下面可查看定价,库存,交付和生命周期等信息

>>Kyocera(京瓷)